

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC3429BES6#TRPBF

(Engineering Calculation)

TSOT-23

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TOTAL MASS (g): 0.012542

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000567	1000000	4526.5004688	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.00482	975000	36539.5625	
		Iron (Fe)	7439-89-6	0.000113	24000	9069.90234375	
		Phosphorus (P)	7723-14-0	0.000001	300	79.731602075	
		Zinc (Zn)	7440-66-6	0.000003	700	239.200942903	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-96-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		<b>Lead Frame Total:</b>			<b>0.004899</b>	<b>1000000</b>	<b>374668.40625</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0	
		Exter. Plating Sn	7440-31-5	0.000644	1000000	51329.0117188	
		<b>External Plating Total:</b>			<b>0.000644</b>	<b>1000000</b>	<b>51329.0117188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0	
		Inter. Plating Ag	7440-22-4	0.000080	1000000	6178.69140625	
		<b>Internal Plating Total:</b>			<b>0.000080</b>	<b>1000000</b>	<b>6378.69140625</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000409	750000	32611.0605469	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000136	250000	10847.7767672	
		<b>Die Attach Total:</b>			<b>0.000545</b>	<b>1000000</b>	<b>43454.839375</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.000772	130000
Bromine (Br)	40093-93-8			0.000000	0	0	
Silica (SiO2)	60676-86-0			0.004930	830000	393086.84375	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000208	35000	16584.5976562	
Carbon Black (C)	1333-86-4			0.000030	5000	2392.00927734	
<b>Encapsulation Total:</b>					<b>0.005940</b>	<b>1000000</b>	<b>473617.84375</b>
Bond Wire Estimated	AFW/TANAKA/Kn			Gold (Au)	7440-57-5	0.000067	1000000

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